



Features

- ESD Protect for 5 Lines with Unidirectional.
- Provide Transient protection for each line directly to
IEC 61000-4-2 (ESD) $\pm 16\text{kV}$ (air), $\pm 12\text{kV}$ (contact)
IEC 61000-4-4 (EFT) 40A (5/50ns)
- For low operating voltage applications: 3.3V maximum
- Fast turn-on and Low clamping voltage
- Array of surge rated equivalent TVS diodes
- Small package saves board space
- Solid-state silicon-avalanche and active circuit triggering technology
- **Green Part**

Applications

- Cellular Handsets and Accessories
- Small Panel Modules
- PDA's
- Portable Devices
- Digital Cameras
- Touch Panels
- Notebooks and Handhelds
- MP3 Players
- Peripherals

Description

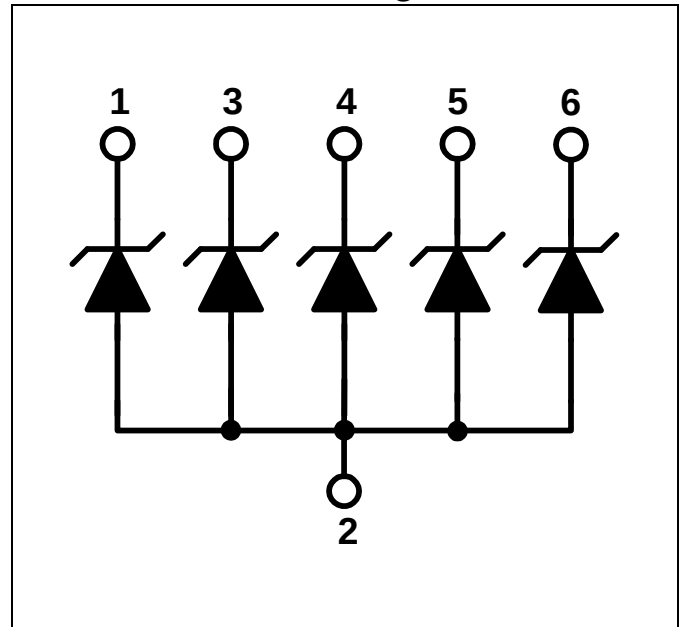
AZ2013-05C is a design which includes ESD rated clamping cell arrays to protect the power lines or data/control lines in an electronic systems. The AZ2013-05C has been specifically designed to protect sensitive components which are connected to power and control lines from over-voltage caused by Electrostatic Discharging (ESD), Electrical Fast Transients (EFT), and Cable Discharge Event (CDE).

AZ2013-05C is a unique design which includes proprietary clamping cells in a single package. During transient conditions, the proprietary clamping cells prevent over-voltage on the power lines or control lines, protecting any downstream components.

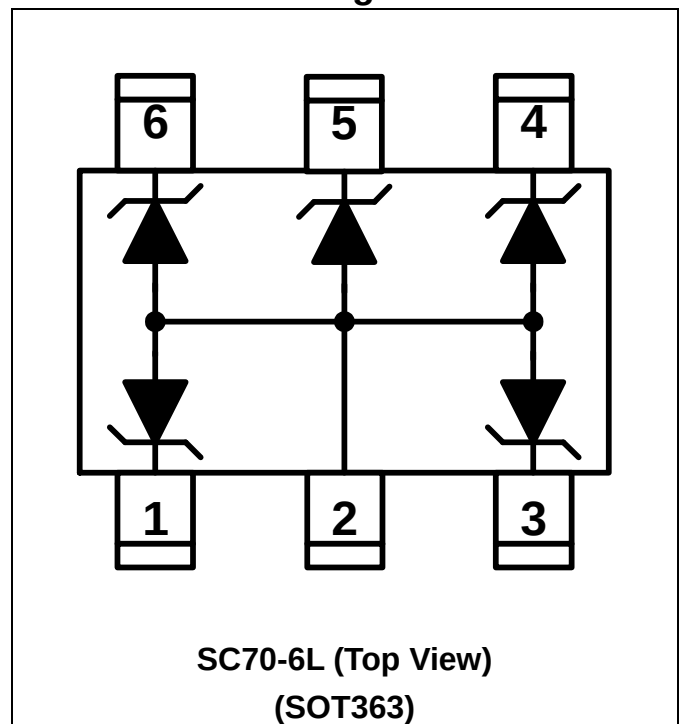
AZ2013-05C may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4

($\pm 15\text{kV}$ air, $\pm 8\text{kV}$ contact discharge).

Circuit Diagram



Pin Configuration



SC70-6L (Top View)
(SOT363)

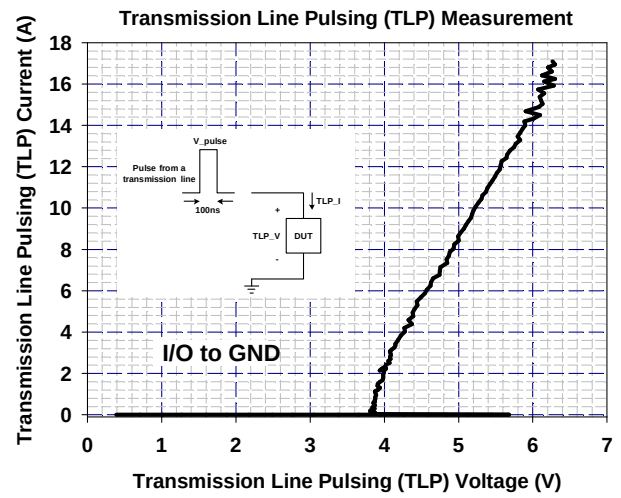
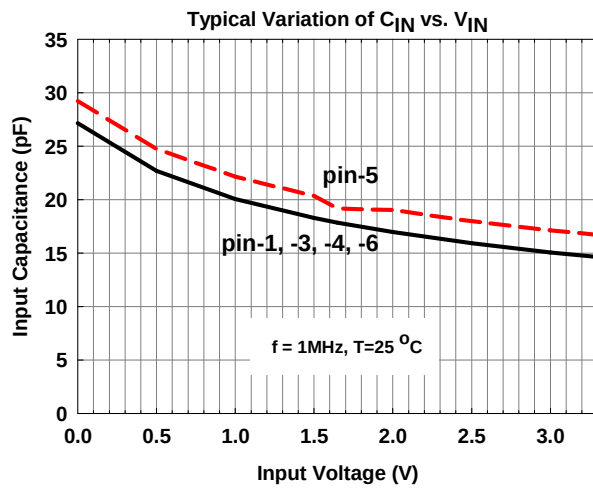
SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS			
PARAMETER	PARAMETER	RATING	UNITS
Operating Supply Voltage (pin-1,-3, -4, -5, -6 to pin-2)	V_{DC}	3.8	V
pin-1,-3, -4, -5, -6 to pin-2 ESD per IEC 61000-4-2 (Air)	V_{ESD-1}	± 16	kV
pin-1,-3, -4, -5, -6 to pin-2 ESD per IEC 61000-4-2 (Contact)		± 12	
Lead Soldering Temperature	T_{SOL}	260 (10 sec.)	$^{\circ}C$
Operating Temperature	T_{OP}	-55 to +85	$^{\circ}C$
Storage Temperature	T_{STO}	-55 to +150	$^{\circ}C$

ELECTRICAL CHARACTERISTICS						
PARAMETER	SYMBOL	CONDITIONS	MINI	TYP	MAX	UNITS
Reverse Stand-Off Voltage	V_{RWM}	pin-1,-3, -4, -5, -6 to pin-2, $T=25^{\circ}C$.			3.3	V
Reverse Leakage Current	I_{Leak}	$V_{RWM} = 3.3V$, $T=25^{\circ}C$, pin-1,-3, -4, -5, -6 to pin-2.			2	μA
Reverse Breakdown Voltage	V_{BV}	$I_{BV} = 1mA$, $T=25^{\circ}C$, pin-1,-3, -4, -5, -6 to pin-2	4.5		6.5	V
Forward Voltage	V_F	$I_F = 15mA$, $T=25^{\circ}C$, pin-2 to pin-1,-3, -4, -5, -6	0.6	0.85	1	V
ESD Clamping Voltage	V_{clamp}	IEC 61000-4-2 +6kV, $T=25^{\circ}C$, Contact mode, pin-1,-3, -4, -5, -6 to pin-2.		6.5		V
ESD Dynamic Turn-on Resistance	$R_{dynamic}$	IEC 61000-4-2 0~+6kV, $T=25^{\circ}C$, Contact mode, pin-1,-3, -4, -5, -6 to pin-2.		0.16		Ω
Channel Input Capacitance	C_{IN}	$V_R = 0V$, $f = 1MHz$, $T=25^{\circ}C$, pin-1,-3, -4, -6 to pin-2.		27		pF
		$V_R = 0V$, $f = 1MHz$, $T=25^{\circ}C$, pin-5 to pin-2.		29		



Typical Characteristics



Applications Information

The AZ2013-05C is designed to protect five lines against System ESD/EFT/CDE pulses by clamping them to an acceptable reference.

The usage of the AZ2013-05C is shown in Fig. 1. Protected lines, such as data lines, control lines, or power lines, are connected at pin 1, 3, 4, 5 and 6. The pin 2 should be connected directly to a ground plane on the board. All path lengths connected to the pins of AZ2013-05C should be kept as short as possible to minimize parasitic inductance in the board traces.

In order to obtain enough suppression of ESD induced transient, good circuit board is critical. Thus, the following guidelines are recommended:

- Minimize the path length between the protected lines and the AZ2013-05C.
- Place the AZ2013-05C near the input terminals or connectors to restrict transient coupling.
- The ESD current return path to ground should be kept as short as possible.
- Use ground planes whenever possible.
- NEVER route critical signals near board edges and near the lines which the ESD transient easily injects to.

Fig. 2 shows an example of PCB layout with the AZ2013-05C.

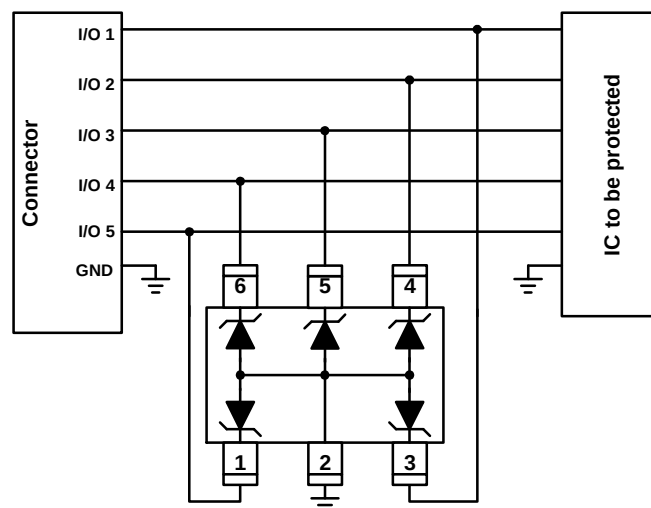


Fig. 1

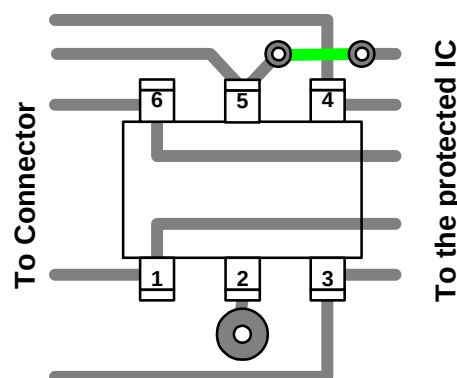
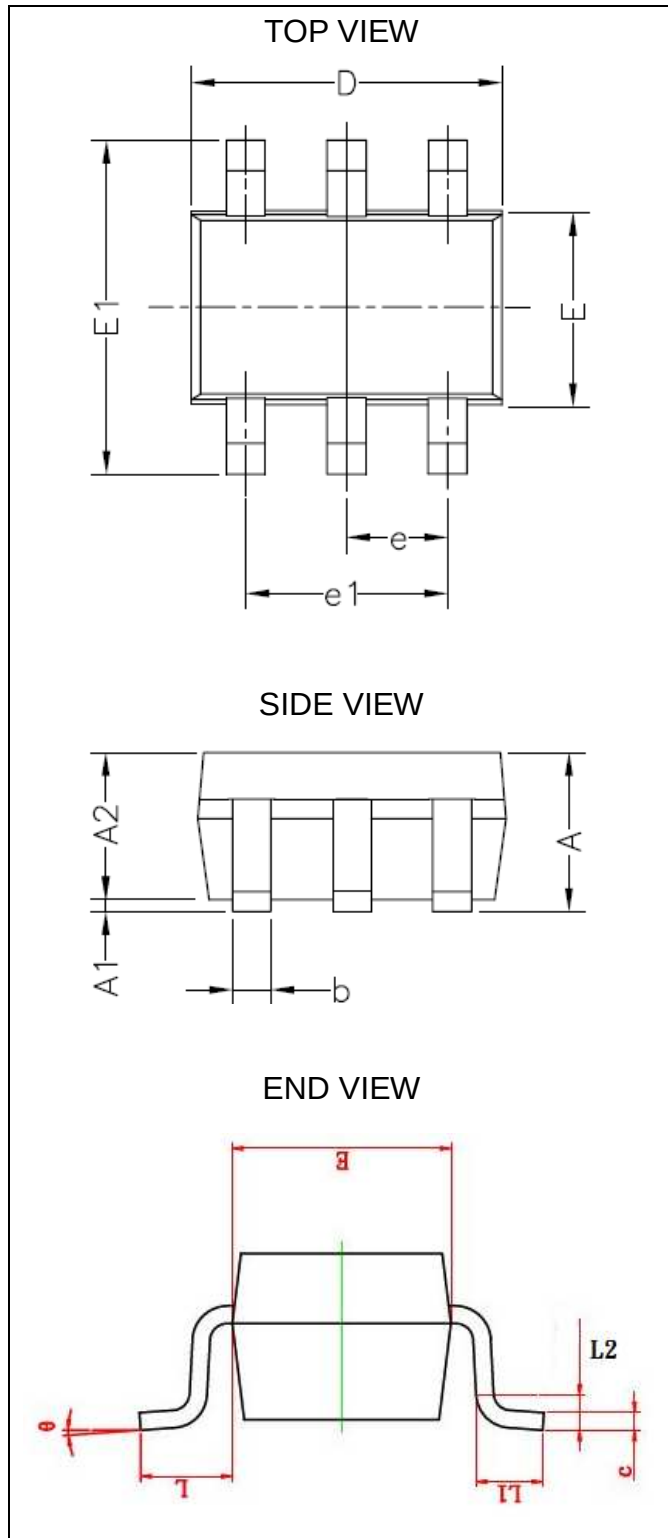


Fig. 2



Mechanical Details

SC70-6L (SOT363)
PACKAGE DIAGRAMS



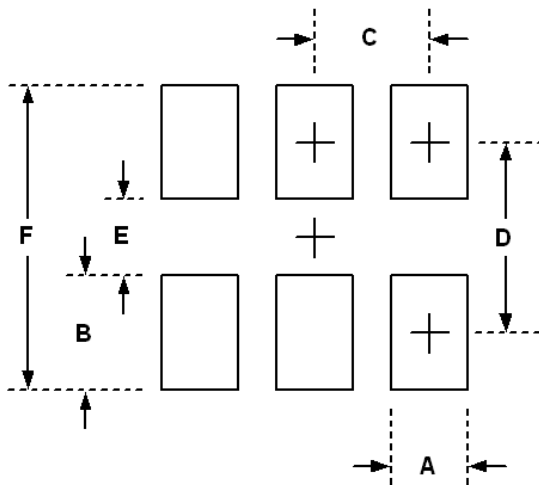
PACKAGE DIMENSIONS

Symbol	Millimeters		Inches	
	min	max	min	max
A	0.90	1.10	0.036	0.044
A1	0.00	0.10	0.000	0.004
A2	0.875	1.00	0.035	0.040
b	0.15	0.40	0.006	0.016
C	0.08	0.15	0.003	0.006
D	1.90	2.20	0.076	0.087
E	1.15	1.35	0.046	0.054
E1	2.00	2.45	0.080	0.096
e	0.65 BSC		0.026 BSC	
e1	1.30 BSC		0.052 BSC	
L	0.475 REF		0.019 REF	
L1	0.300 REF		0.012 REF	
L2	0.200 REF		0.007 REF	
θ	0°	8°	0°	8°

Note:

1. All dimensions are in millimeters, and the dimensions in inches are for reference only.
2. 1mm = 40 mils = 0.04 inches.

LAND LAYOUT

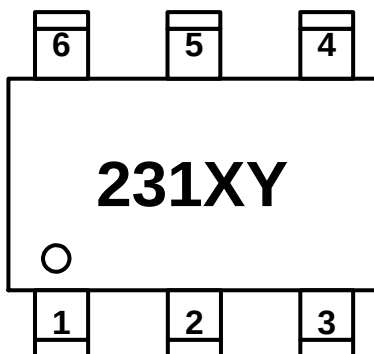


Dimensions		
Index	Millimeter	Inches
A	0.40	0.016
B	0.85	0.033
C	0.65	0.026
D	1.85	0.073
E	1.00	0.039
F	2.70	0.106

Notes:

This LAND LAYOUT is for reference purposes only. Please consult your manufacturing partners to ensure your company's PCB design guidelines are met.

MARKING CODE



Part Number	Marking Code
AZ2013-05C	231XY
AZ2013-05C (Engineering Samples)	A25U

231 = Device Code

X = Date Code

Y = Control Code

Ordering Information

PN#	Material	Type	Reel size	MOQ/internal box	MOQ/carton
AZ2013-05C.R7G	Green	T/R	7 inch	4 reel=12,000/box	6 box=72,000/carton



Revision History

Revision	Modification Description
Revision 2008/05/31	Preliminary Release.
Revision 2011/07/05	Formal Release.